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General Information

Series	SMD Comm COG HV Flex
Style	SMD Chip
Description	SMD, MLCC, FT-CAP, Ultra-Stable
Features	FT-CAP, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	87 mg
Shelf Life	78 Weeks
MSL	1

Dimensions

Chip Size	1812
L	4.5mm +/-0.4mm
W	3.2mm +/-0.3mm
T	1.6mm +/-0.20mm
S	2.3mm MIN
B	0.7mm +/-0.35mm

Packaging Specifications

Packaging	T&R, 330mm, Plastic Tape
Packaging Quantity	4000

Specifications

Capacitance	470 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	10%
Voltage DC	2500 VDC
Dielectric Withstanding Voltage	3,000 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

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